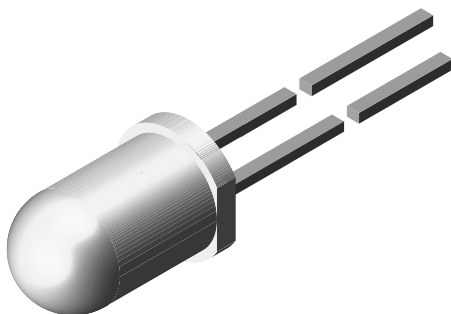




High Speed Infrared Emitting Diode, 870 nm, GaAlAs Double Hetero



DESCRIPTION

TSFF6210 is an infrared, 870 nm emitting diode in GaAlAs double hetero (DH) technology with high radiant power and high speed, molded in a clear, untinted plastic package.

FEATURES

- Package type: leaded
- Package form: T-1 $\frac{3}{4}$
- Dimensions (in mm): \varnothing 5
- Peak wavelength: $\lambda_p = 870$ nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\varphi = \pm 10^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- High modulation bandwidth: $f_c = 24$ MHz
- Good spectral matching with Si photodetectors
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Infrared video data transmission between Camcorder and TV set
- Free air data transmission systems with high modulation frequencies or high data transmission rate requirements
- Smoke-automatic fire detectors

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	φ (°)	λ_p (nm)	t_r (ns)
TSFF6210	180	± 10	870	15

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TSFF6210	Bulk	MOQ: 4000 pcs, 4000 pcs/bulk	T-1 $\frac{3}{4}$

Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100\text{ }\mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	180	mW
Junction temperature		T_j	100	$^{\circ}\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	$t \leq 5\text{ s}, 2\text{ mm from case}$	T_{sd}	260	$^{\circ}\text{C}$
Thermal resistance junction to ambient	J-STD-051, leads 7 mm, soldered on PCB	R_{thJA}	230	K/W

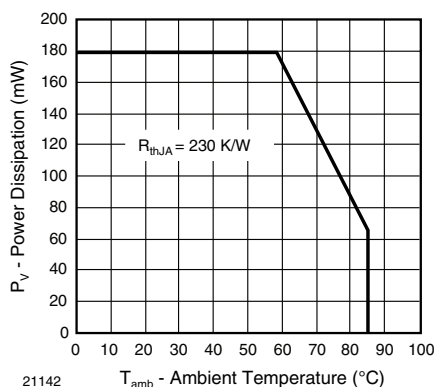


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

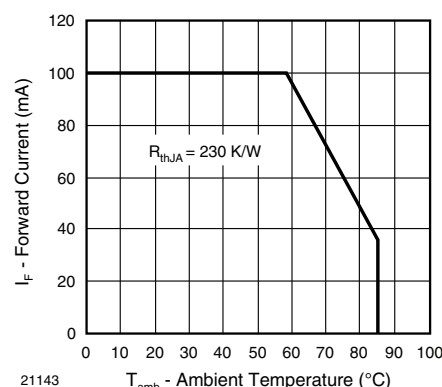


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	V_F	-	1.5	1.8	V
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	V_F	-	2.3	3.0	V
Temperature coefficient of V_F	$I_F = 1\text{ mA}$	TK_{V_F}	-	-1.8	-	mV/K
Reverse current	$V_R = 5\text{ V}$	I_R	-	-	10	μA
Junction capacitance	$V_R = 0\text{ V}, f = 1\text{ MHz}, E = 0$	C_j	-	125	-	pF
Radiant intensity	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	I_e	90	180	450	mW/sr
	$I_F = 1\text{ A}, t_p = 100\text{ }\mu\text{s}$	I_e	-	1800	-	mW/sr
Radiant power	$I_F = 100\text{ mA}, t_p = 20\text{ ms}$	ϕ_e	-	50	-	mW
Temperature coefficient of ϕ_e	$I_F = 100\text{ mA}$	TK_{ϕ_e}	-	-0.35	-	%/K
Angle of half intensity		φ	-	± 10	-	$^{\circ}$
Peak wavelength	$I_F = 100\text{ mA}$	λ_p	-	870	-	nm
Spectral bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$	-	40	-	nm
Temperature coefficient of λ_p	$I_F = 100\text{ mA}$	TK_{λ_p}	-	0.25	-	nm/K
Rise time	$I_F = 100\text{ mA}$	t_r	-	15	-	ns
Fall time	$I_F = 100\text{ mA}$	t_f	-	15	-	ns
Cut-off frequency	$I_{DC} = 70\text{ mA}, I_{AC} = 30\text{ mA pp}$	f_c	-	24	-	MHz
Virtual source diameter		d	-	3.7	-	mm



BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

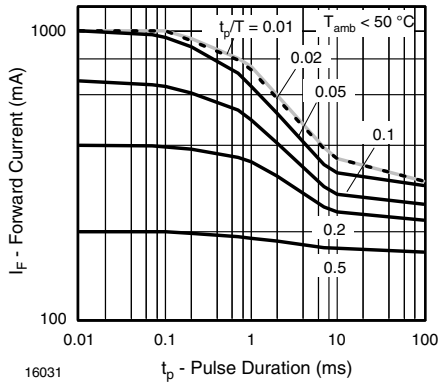


Fig. 3 - Pulse Forward Current vs. Pulse Duration

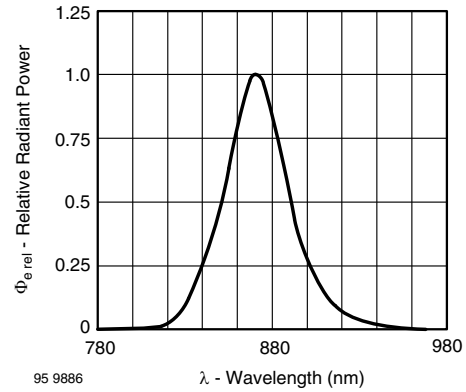


Fig. 6 - Relative Radiant Power vs. Wavelength

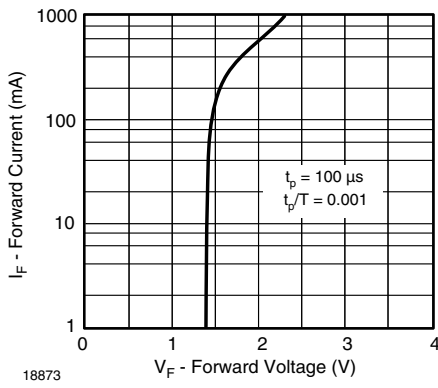


Fig. 4 - Forward Current vs. Forward Voltage

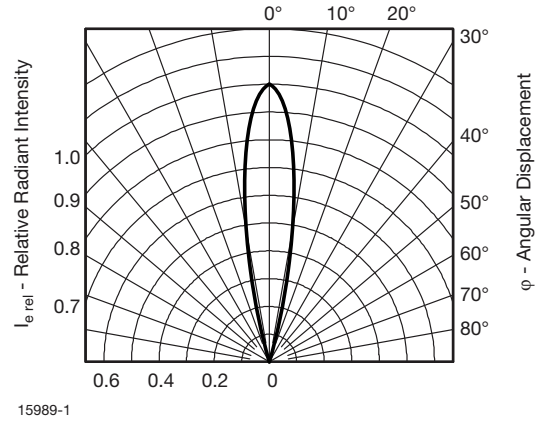


Fig. 7 - Relative Radiant Intensity vs. Angular Displacement

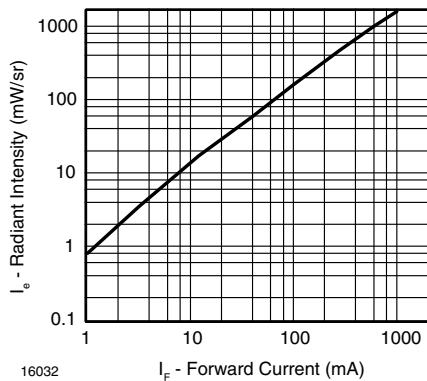


Fig. 5 - Radiant Intensity vs. Forward Current

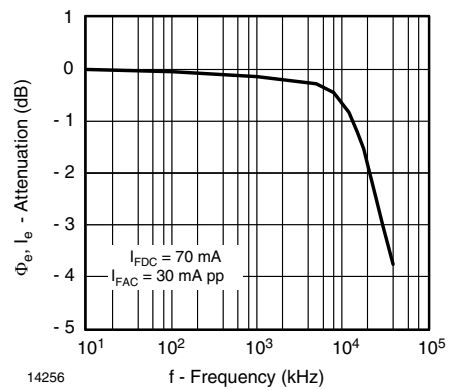
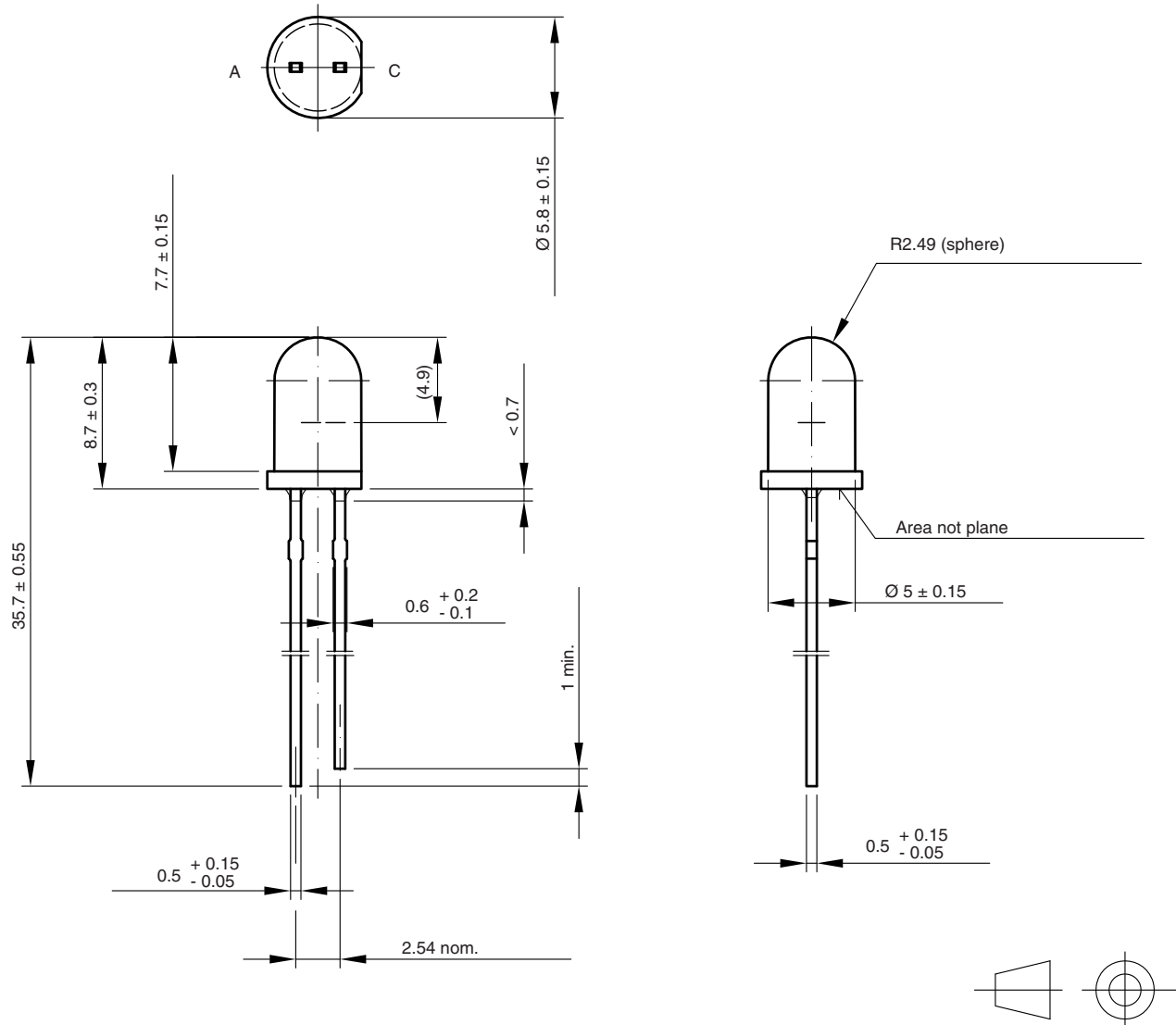


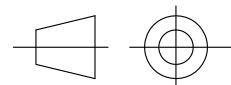
Fig. 8 - Attenuation vs. Frequency



PACKAGE DIMENSIONS in millimeters



6.544-5259.09-4
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20161



technical drawings
according to DIN
specifications



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